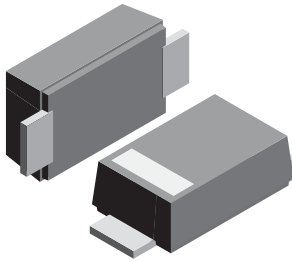


Hyperfast Rectifier, 1 A FRED Pt[®]



SMF (DO-219AB)



FEATURES

- Hyperfast recovery time, reduced Q_{rr} , and soft recovery
- 175 °C maximum operating junction temperature
- Specific for output and snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

| PRODUCT SUMMARY | |
|-----------------|----------------|
| Package | DO-219AB (SMF) |
| $I_{F(AV)}$ | 1 A |
| V_R | 200 V |
| V_F at I_F | 0.93 V |
| t_{rr} | 25 ns |
| T_J max. | 175 °C |
| Diode variation | Single die |

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in snubber, boost, lighting, piezo-injection, as high frequency rectifiers and freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

| ABSOLUTE MAXIMUM RATINGS | | | | |
|---|----------------|-----------------------------|------------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | VALUES | UNITS |
| Peak repetitive reverse voltage | V_{RRM} | | 200 | V |
| Average rectified forward current | $I_{F(AV)}$ | $T_C = 160\text{ °C}^{(1)}$ | 1 | A |
| Non-repetitive peak surge current | I_{FSM} | $T_J = 25\text{ °C}$ | 40 | |
| Operating junction and storage temperatures | T_J, T_{Stg} | | -65 to 175 | °C |

Note

(1) Device on PCB with 8 mm x 16 mm soldering lands

| ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified) | | | | | | |
|--|---------------|---|------|--------------|-------------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
| Breakdown voltage, blocking voltage | V_{BR}, V_R | $I_R = 100\ \mu\text{A}$ | 200 | - | - | V |
| Forward voltage | V_F | $I_F = 1\ \text{A}$ $I_F = 1\ \text{A}, T_J = 125\text{ °C}$ | - | 0.87 0.74 | 0.93 0.8 | |
| Reverse leakage current | I_R | $V_R = V_R$ rated $T_J = 125\text{ °C}, V_R = V_R$ rated | - | - | 2 8 | μA |
| Junction capacitance | C_T | $V_R = 200\ \text{V}$ | - | 5 | - | pF |



| DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified) | | | | | | | |
|--|-----------|--|-----------------------------------|------|------|-------|----|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | |
| Reverse recovery time | t_{rr} | $I_F = 1.0\text{ A}$, $dI_F/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$ | - | 26 | - | ns | |
| | | $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$ | - | - | 25 | | |
| | | $T_J = 25\text{ }^\circ\text{C}$ | - | 16 | - | | |
| | | $T_J = 125\text{ }^\circ\text{C}$ | - | 23 | - | | |
| Peak recovery current | I_{RRM} | $I_F = 1\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 160\text{ V}$ | $T_J = 25\text{ }^\circ\text{C}$ | - | 1.6 | - | A |
| | | | $T_J = 125\text{ }^\circ\text{C}$ | - | 2.5 | - | |
| Reverse recovery charge | Q_{rr} | | $T_J = 25\text{ }^\circ\text{C}$ | - | 13 | - | nC |
| | | | $T_J = 125\text{ }^\circ\text{C}$ | - | 30 | - | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | |
|--|----------------|--|--------|------|------|---------------------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
| Maximum junction and storage temperature range | T_J, T_{Stg} | | -65 | - | 175 | $^\circ\text{C}$ |
| Thermal resistance, junction to case | R_{thJC} | Device mounted on PCB with 8 mm x 16 mm soldering lands | - | - | 17 | $^\circ\text{C}/\text{W}$ |
| Thermal resistance, junction to ambient | R_{thJA} | Device mounted on PCB with 2 mm x 3.5 mm soldering lands | - | - | 140 | |
| Approximate weight | | | 0.015 | | | g |
| | | | 0.0005 | | | oz. |
| Marking device | | Case style SMF (DO-219AB) | DH | | | |

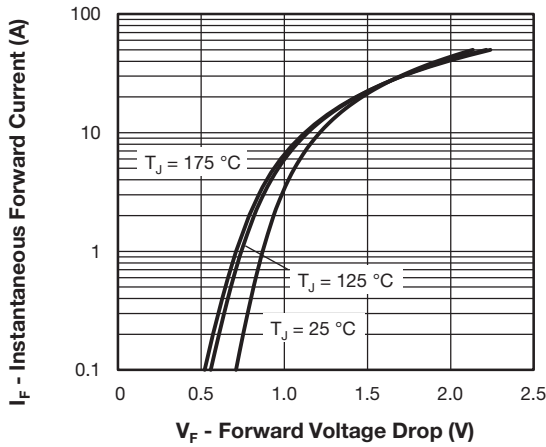


Fig. 1 - Typical Forward Voltage Drop Characteristics

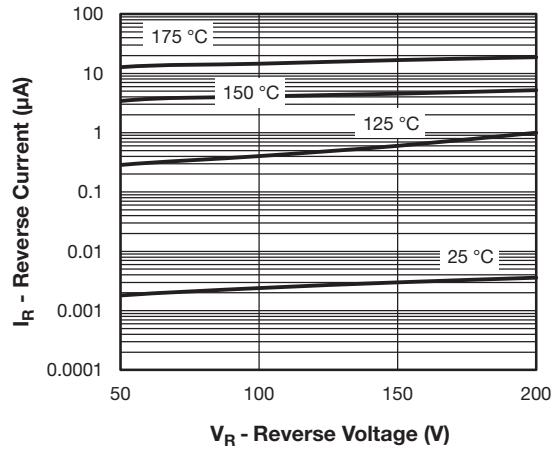


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

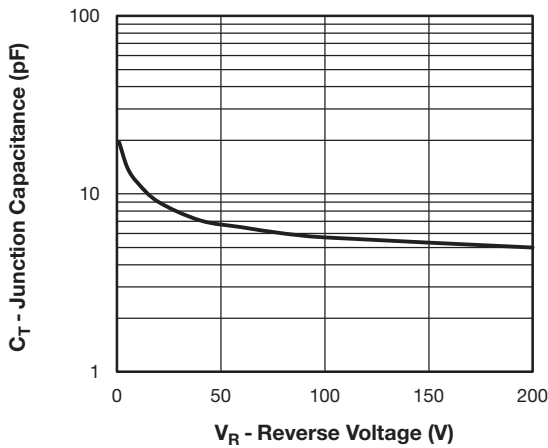


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

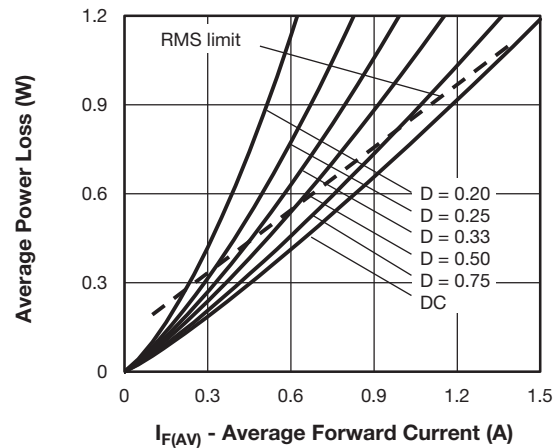


Fig. 5 - Forward Power Loss Characteristics

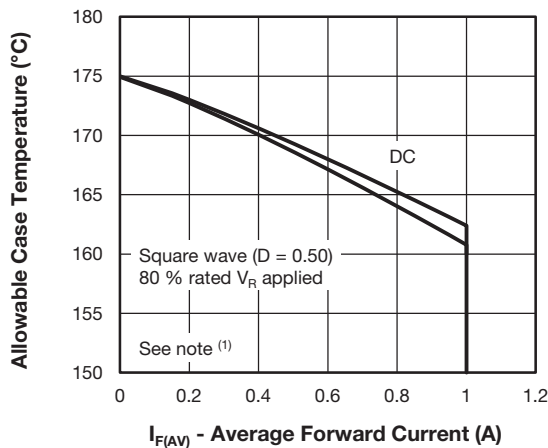


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

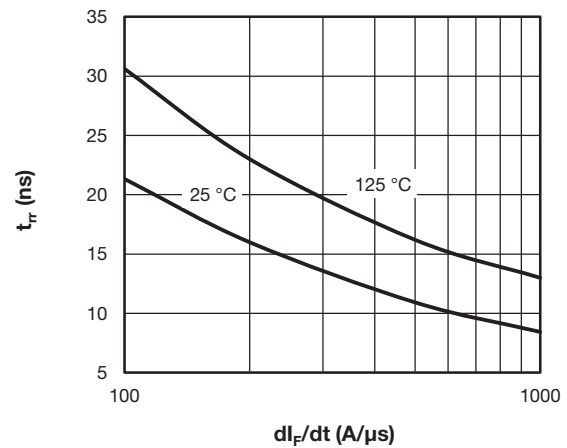


Fig. 6 - Typical Reverse Recovery Time vs. dI_F/dt

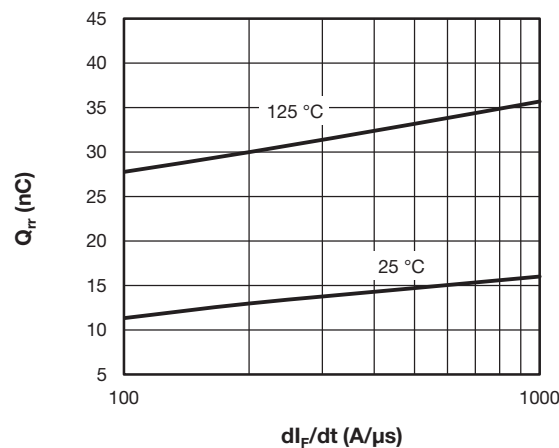
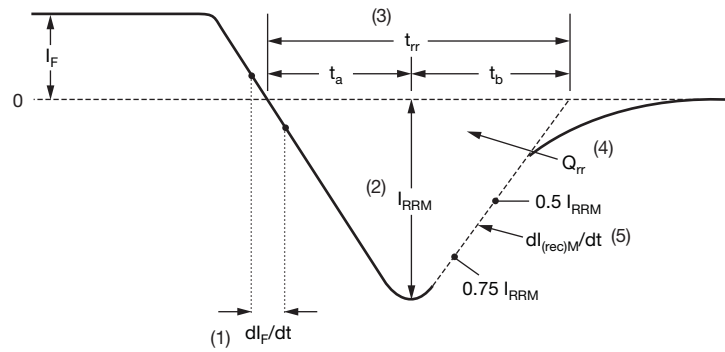


Fig. 7 - Typical Stored Charge vs. dI_F/dt

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = Forward Power Loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see Fig. 6);
 P_{dREV} = Inverse Power Loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R



- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 8 - Reverse Recovery Waveform and Definitions

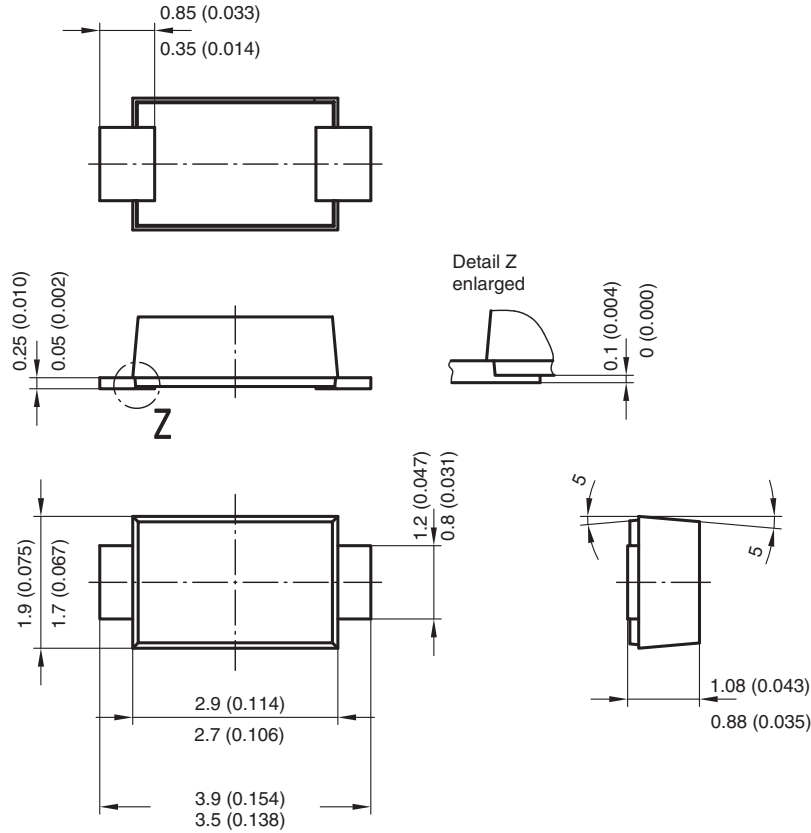
| ORDERING INFORMATION (Example) | | | |
|---------------------------------------|-------------------|------------------------|------------------------------------|
| PREFERRED P/N | QUANTITY PER REEL | MINIMUM ORDER QUANTITY | PACKAGING DESCRIPTION |
| VS-1EFH02WHM3-18 | 10 000 | 10 000 | 13" diameter plastic tape and reel |

| LINKS TO RELATED DOCUMENTS | |
|-----------------------------------|--|
| Dimensions | www.vishay.com/doc?95572 |
| Part marking information | www.vishay.com/doc?95563 |
| Packaging information | www.vishay.com/doc?95577 |

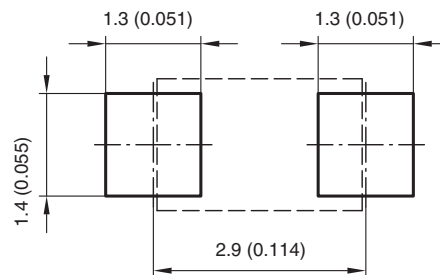


DO-219AB (SMF)

DIMENSIONS in millimeters (inches)



Foot print recommendation:



Created - Date: 15. February 2005
 Rev. 3 - Date: 13. March 2007
 Document no.:S8-V-3915.01-001 (4)
 17247



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